



# P-Channel 20-V (D-S) MOSFET

PRODUCT SUMMARY						
V <sub>DS</sub> (V)	$R_{DS(on)}\left(\Omega\right)$	I <sub>D</sub> (A)	Q <sub>g</sub> (Typ.)			
	$0.0275$ at $V_{GS} = -4.5 \text{ V}$	- 8.0 <sup>a</sup>				
- 20	0.034 at V <sub>GS</sub> = - 2.5 V	2.5 V - 7.9 2				
	0.045 at V <sub>GS</sub> = - 1.8 V	- 2.2				

TSOP-6

#### **FEATURES**

- Halogen-free According to IEC 61249-2-21 Definition
- TrenchFET<sup>®</sup> Power MOSFET
- PWM Optimized
- 100 % R<sub>a</sub> Tested
- Compliant to RoHS Directive 2002/95/EC

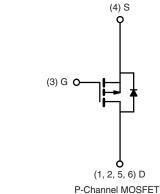


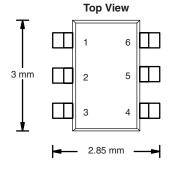


#### **APPLICATIONS**

- · Load Switch
- PA Switch
- · Battery Switch

Lot Traceability and Date Code





Ordering Information: Si3493BDV-T1-E3 (Lead (Pb)-free)

Si3493BDV-T1-GE3 (Lead (Pb)-free and Halogen-free)

ABSOLUTE MAXIMUM RATINGS T<sub>A</sub> = 25 °C, unless otherwise noted Symbol **Parameter** Limit Unit Drain-Source Voltage - 20  $V_{DS}$ Gate-Source Voltage  $\overline{V}_{GS}$ ± 8.0 T<sub>C</sub> = 25 °C - 8.0<sup>a</sup> T<sub>C</sub> = 70 °C - 7.03 Continuous Drain Current (T<sub>J</sub> = 150 °C)  $I_D$  $T_A = 25 \, ^{\circ}C$ - 7.0<sup>b, c</sup> T<sub>A</sub> = 70 °C - 5.8<sup>b, c</sup> Pulsed Drain Current - 25  $I_{DM}$  $T_C = 25 \, ^{\circ}C$ - 2.48 Continuous Source-Drain Diode Current ls T<sub>A</sub> = 25 °C - 1.73<sup>b, c</sup> T<sub>C</sub> = 25 °C 2.97 T<sub>C</sub> = 70 °C 1.9 Maximum Power Dissipation  $P_D$ W T<sub>A</sub> = 25 °C 2.08<sup>b, c</sup> 1.33<sup>b, c</sup> T<sub>A</sub> = 70 °C T<sub>J</sub>, T<sub>stg</sub> Operating Junction and Storage Temperature Range - 55 to 150

Marking Code

AK XXX

Part # Code

THERMAL RESISTANCE RATINGS							
Parameter		Symbol	Typical	Maximum	Unit		
Maximum Junction-to-Ambient <sup>b, d</sup>	t ≤ 5 s	R <sub>thJA</sub>	50	60	°C/W		
Maximum Junction-to-Foot (Drain)	Steady State	$R_{thJF}$	35	42	]		

#### Notes:

- a. Package limited.
- b. Surface Mounted on 1" x 1" FR4 board.
- c. t = 5 s
- d. Maximum under Steady State conditions is 90 °C/W.

# Si3493BDV

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Parameter	Symbol	Test Conditions	Min.	Тур.	Max.	Unit	
Static							
Drain-Source Breakdown Voltage	V <sub>DS</sub>	$V_{GS} = 0 \text{ V, } I_D = -250 \mu\text{A}$	- 20			V	
V <sub>DS</sub> Temperature Coefficient	$\Delta V_{DS}/T_{J}$	J 050 ·· A		-14.1		mV/°C	
V <sub>GS(th)</sub> Temperature Coefficient	$\Delta V_{GS(th)}/T_J$	I <sub>D</sub> = - 250 μA		2.85			
Gate-Source Threshold Voltage	V <sub>GS(th)</sub>	$V_{DS} = V_{GS}$ , $I_{D} = -250 \mu A$	- 0.4		- 0.9	V	
Gate-Source Leakage	I <sub>GSS</sub>	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 8 \text{ V}$			± 100	nA	
Zovo Coto Voltago Droin Current		V <sub>DS</sub> = - 20 V, V <sub>GS</sub> = 0 V			- 1		
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	$V_{DS} = -20 \text{ V}, V_{GS} = 0 \text{ V}, T_{J} = 55 ^{\circ}\text{C}$			- 10	μΑ	
On-State Drain Current <sup>a</sup>	I <sub>D(on)</sub>	$V_{DS} \ge -5 \text{ V}, V_{GS} = -4.5 \text{ V}$	- 25			Α	
	` '	V <sub>GS</sub> = - 4.5 V, I <sub>D</sub> = - 7 A		0.023	0.0275	Ω	
Drain-Source On-State Resistance <sup>a</sup>	R <sub>DS(on)</sub>	$V_{GS} = -2.5 \text{ V}, I_D = -3.5 \text{ A}$		0.0284	0.034		
	,	V <sub>GS</sub> = - 1.8 V, I <sub>D</sub> = - 2.2 A		0.0347	0.045		
Forward Transconductance <sup>a</sup>	9 <sub>fs</sub>	V <sub>DS</sub> = 10 V, I <sub>D</sub> = - 7 A		24.3		S	
Dynamic <sup>b</sup>							
Input Capacitance	C <sub>iss</sub>			1805		pF	
Output Capacitance	C <sub>oss</sub>	V <sub>DS</sub> = - 10 V, V <sub>GS</sub> = 0 V, f = 1 MHz		285			
Reverse Transfer Capacitance	C <sub>rss</sub>			245			
Total Cata Chausa	$Q_g$ $V_{DS} = -10 \text{ V}, V_{GS} = -5.0 \text{ V}, I_D = -7 \text{ A}$ $V_{DS} = -10 \text{ V}, V_{GS} = -4.5 \text{ V}, I_D = -7 \text{ A}$	$V_{DS} = -10 \text{ V}, V_{GS} = -5.0 \text{ V}, I_{D} = -7 \text{ A}$		29	43.5	nC	
Total Gate Charge				26.2	39.3		
Gate-Source Charge			1.45		nC		
Gate-Drain Charge	$Q_{gd}$			7.14			
Gate Resistance	$R_{g}$	f = 1 MHz		6.5	10	Ω	
Turn-On Delay Time	t <sub>d(on)</sub>			22	33		
Rise Time	t <sub>r</sub>	V 10 V B 20 C		72	108	ns	
Turn-Off Delay Time	t <sub>d(off)</sub>	$V_{DD}$ = - 10 V, $R_L$ = 2.0 Ω $I_D \cong$ - 5.0 A, $V_{GEN}$ = - 4.5 V, $R_α$ = 1 Ω		75	113		
Fall Time	t <sub>f</sub>	$I_D = -3.0 \text{ A}, \text{ V}_{GEN} = -4.3 \text{ V}, \text{ H}_g = 1.52$		84	126		
<b>Drain-Source Body Diode Characteristi</b>	cs						
Continuous Source-Drain Diode Current	I <sub>S</sub>	T <sub>C</sub> = 25 °C			- 2.48	A	
Pulse Diode Forward Current <sup>a</sup>	I <sub>SM</sub>				- 25		
Body Diode Voltage	V <sub>SD</sub>	I <sub>S</sub> = - 2.5 A	- 0.8		- 1.2	V	
Body Diode Reverse Recovery Time	t <sub>rr</sub>			52	78	ns	
Body Diode Reverse Recovery Charge	Q <sub>rr</sub>	L = 2.1 A dl/dt = 100 A/up T = 25 °C		49.5	74.3	nC	
Reverse Recovery Fall Time	t <sub>a</sub>	$I_F = 2.1 \text{ A, dI/dt} = 100 \text{ A/}\mu\text{s, T}_J = 25 ^{\circ}\text{C}$		23.5		ns	
Reverse Recovery Rise Time	t <sub>b</sub>			28.5			

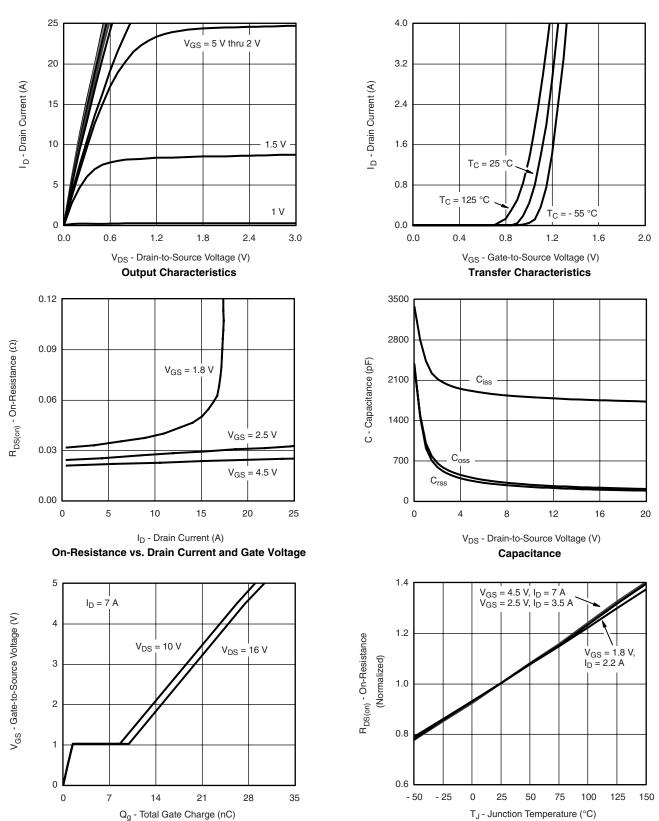
#### Notes:

- a. Pulse test; pulse width  $\leq$  300  $\mu s,$  duty cycle  $\leq$  2 %
- b. Guaranteed by design, not subject to production testing.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.



#### TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted

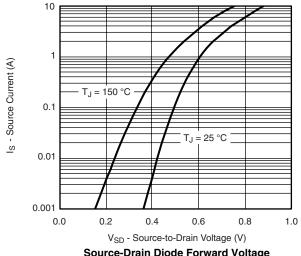


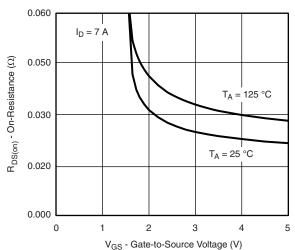
**Gate Charge** 

On-Resistance vs. Junction Temperature

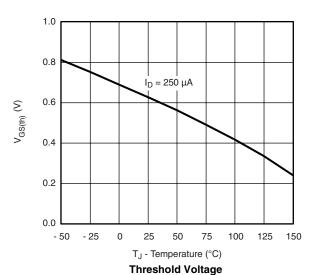
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#### TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted

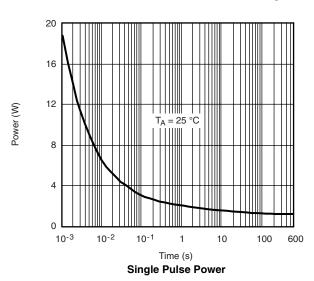


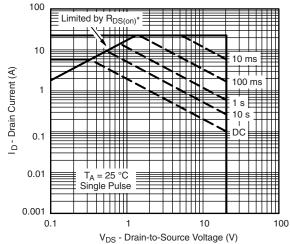


#### Source-Drain Diode Forward Voltage









\* V<sub>GS</sub> > minimum V<sub>GS</sub> at which R<sub>DS(on)</sub> is specified

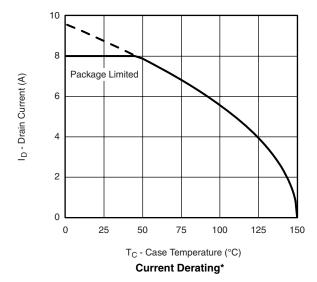
Safe Operating Area, Junction-to-Ambient

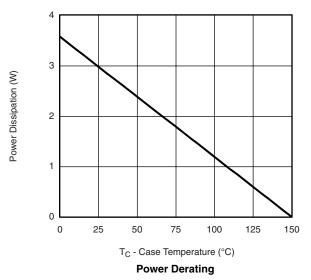




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#### TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



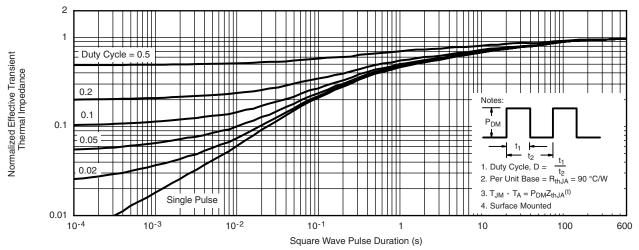


<sup>\*</sup> The power dissipation  $P_D$  is based on  $T_{J(max)} = 150$  °C, using junction-to-case thermal resistance, and is more useful in settling the upper dissipation limit for cases where additional heatsinking is used. It is used to determine the current rating, when this rating falls below the package limit.

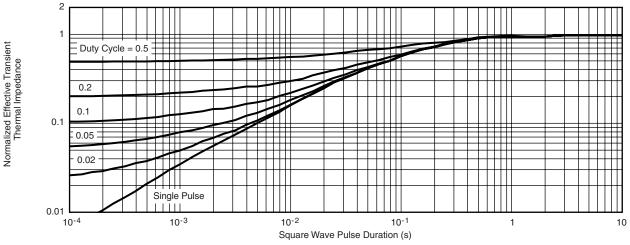
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#### TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



Normalized Thermal Transient Impedance, Junction-to-Ambient



Normalized Thermal Transient Impedance, Junction-to-Foot

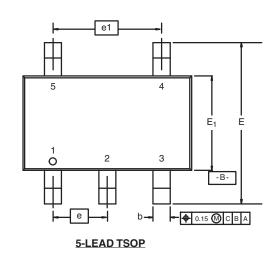
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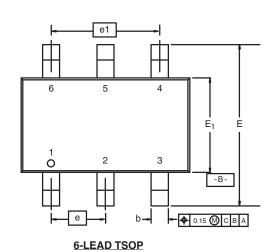


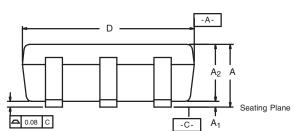


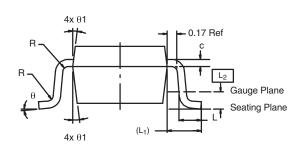
TSOP: 5/6-LEAD

**JEDEC Part Number: MO-193C** 









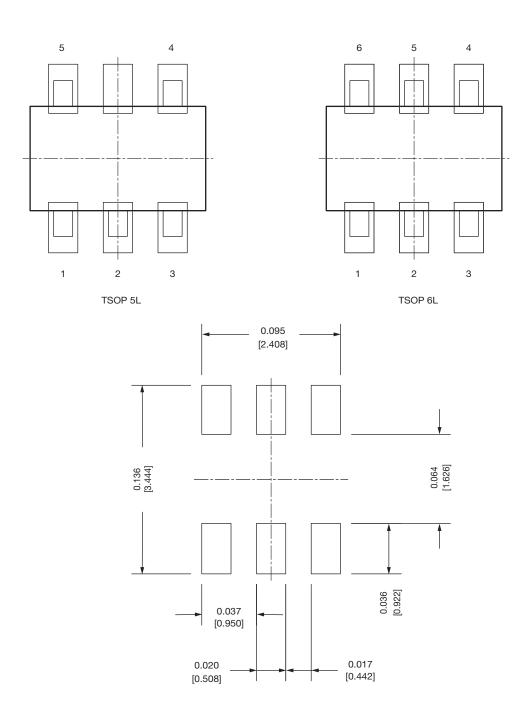
	MILLIMETERS			INCHES			
Dim	Min	Nom	Max	Min	Nom	Max	
Α	0.91	-	1.10	0.036	-	0.043	
A <sub>1</sub>	0.01	-	0.10	0.0004	-	0.004	
A <sub>2</sub>	0.90	-	1.00	0.035	0.038	0.039	
b	0.30	0.32	0.45	0.012	0.013	0.018	
С	0.10	0.15	0.20	0.004	0.006	0.008	
D	2.95	3.05	3.10	0.116	0.120	0.122	
E	2.70	2.85	2.98	0.106	0.112	0.117	
E <sub>1</sub>	1.55	1.65	1.70	0.061	0.065	0.067	
е	0.95 BSC			0.0374 BSC			
e <sub>1</sub>	1.80	1.90	2.00	0.071	0.075	0.079	
L	0.32	-	0.50	0.012	-	0.020	
L <sub>1</sub>	0.60 Ref			0.024 Ref			
L <sub>2</sub>	0.25 BSC			0.010 BSC			
R	0.10	-	-	0.004	-	-	
θ	0°	4°	8°	0°	4°	8°	
$\theta_1$	7° Nom			7° Nom			
ECN: C-06593-Rev. I, 18-Dec-06 DWG: 5540							

Document Number: 71200

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# Recommended Land Pattern For TSOP-5L / TSOP-6L



#### Note

• All dimensions are in inches (millimeter)

ECN: C22-0860-Rev. B, 24-Oct-2022 DWG: 3010



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